Claim Amendments

Please amend claims 1, 9, 10 and 13 as follows:

Listing of Claims

1. (Currently amended) A method of cleaning a process chamber to reduce an amount of nitrogen trifluoride to remove silicon nitride and/or silicon oxide deposits, comprising the steps of:

providing a gas mixture comprising nitrous oxide and nitrogen trifloride trifluoride without the addition of hydrogen and nitrogen gas in wherein [[a]] said nitrous oxide:nitrogen trifluoride volume ratio [[of]] is at least about 0.2;

maintaining a temperature of from about 65°C to about 300°C in said process chamber;

introducing said gas mixture into the process chamber; and

generating a plasma from said gas mixture to clean said chamber.

2. (Original) The method of claim 1 further comprising the step of providing an inert carrier gas in said gas mixture.

- 3. (Original) The method of claim 1 wherein said nitrous oxide:nitrogen trifluoride volume ratio is from at least about 0.2 to about 0.8.
- 4. (Original) The method of claim 3 further comprising the step of providing an inert carrier gas in said gas mixture.
- 5. (Original) The method of claim 2 wherein said inert carrier gas comprises argon.
- 6. (Original) The method of claim 5 wherein said nitrous oxide:nitrogen trifluoride volume ratio is from at least about 0.2 to about 0.8.
 - 7. (Original) The method of claim 2 wherein said inert carrier gas comprises helium.
 - 8. (Original) The method of claim 7 wherein said nitrous oxide:nitrogen triffuoride volume ratio is from at least about 0.2 to about 0.8.
 - 9. (Currently amended) A method of cleaning a process chamber, comprising the steps of:

providing a gas mixture comprising consisting essentially of nitrous oxide, and nitrogen trifluoride, and optionally an inert carrier gas in wherein [[a]] said nitrous oxide:nitrogen trifluoride volume ratio [[oi]] is at least about 0.8 0.2;

introducing said gas mixture into the process chamber; and

generating a plasma from said gas mixture using a radio frequency power of from about 1 watt/cm² to about 20 watts/cm² to clean said chamber.

- 10. (Currently amended) The method of claim 9 further comprising the step of providing adding an inert carrier gas in to said gas mixture.
- 11. (Original) The method of claim 10 wherein said inert carrier gas comprises argon.
- 12. (Original) The method of claim 10 wherein said inert carrier gas comprises helium.

13. (Currently amended) A method of expediting cleaning of a process chamber and reducing an amount of using nitrogen trifluoride, comprising the steps of:

forming a gas mixture by adding nitrous oxide to the nitrogen trifluoride in a nitrous oxide:nitrogen trifluoride volume ratio of at least about 0.2, said gas mixture formed without the addition of hydrogen and nitrogen gas;

maintaining a temperature of from about 65°C to about 300°C in said process chamber;

introducing said gas mixture into the process chamber; and

forming nitric oxide radicals and fluoride radicals in the process chamber by generating a plasma from said gas mixture using a radio frequency power of from about 1 watt/cm² to about 20 watts/cm².

14. (Original) The method of claim 13 further comprising the step of providing an inert carrier gas in said gas mixture.

- 15. (Original) The method of claim 13 wherein said nitrous oxide:nitrogen trifluoride volume ratio is from at least about 0.2 to about 0.8.
- 16. (Original) The method of claim 15 further comprising the step of providing an inert carrier gas in said gas mixture.
- 17. (Original) The method of claim 13 wherein said nitrous oxide:nitrogen trifluoride volume ratio is at least about 0.8.
- 18. (Original) The method of claim 17 further comprising the step of providing an inert carrier gas in said gas mixture.
- 19. (Original) The method of claim 18 wherein said inert carrier gas comprises argon.
- 20. (Original) The method of claim 18 wherein said inert carrier gas comprises belium.